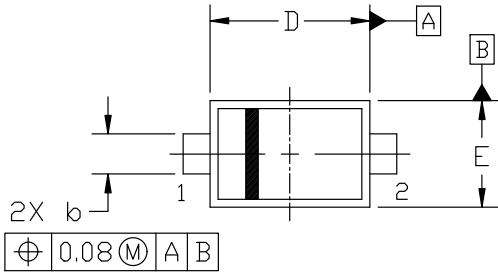


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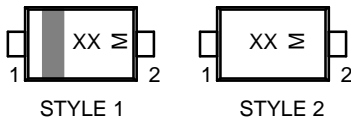
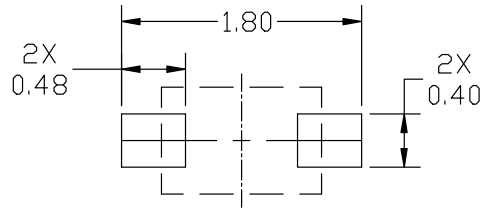
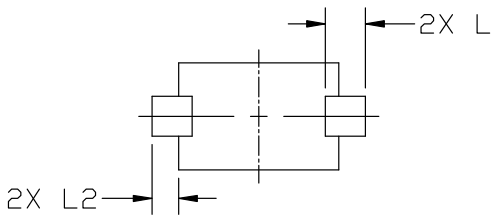
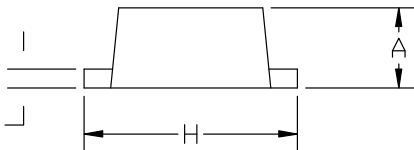
DATE 08 FEB 2024



2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH, MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

MILLIMETERS		
DIM	MIN.	NOM.
0.50	0.50	0.60

AND TOLERANCING PER ASME Y14.5M, 2



XX = Specific Device Code  
M    Date Code

\*For additional information

ing and Mounting Techniques  
Reference manual, SOLDERRM/D.

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:      STYLE 2:  
PIN 1. CATHODE (POLARITY BAND)      NO POLARITY  
2. ANODE

